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Understanding **Embedded - FPGAs (Field Programmable Gate Array)**

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications,

Details

Product Status	Obsolete
Number of LABs/CLBs	-
Number of Logic Elements/Cells	6100
Total RAM Bits	94208
Number of I/O	224
Number of Gates	-
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	484-BBGA
Supplier Device Package	484-FPBGA (23x23)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfec6e-5fn484c

Introduction

The LatticeECP/EC family of FPGA devices is optimized to deliver mainstream FPGA features at low cost. For maximum performance and value, the LatticeECP™ (Economy Plus) FPGA concept combines an efficient FPGA fabric with high-speed dedicated functions. Lattice's first family to implement this approach is the LatticeECP-DSP™ (Economy Plus DSP) family, providing dedicated high-performance DSP blocks on-chip. The LatticeEC™ (Economy) family supports all the general purpose features of LatticeECP devices without dedicated function blocks to achieve lower cost solutions.

The LatticeECP/EC FPGA fabric, which was designed from the outset with low cost in mind, contains all the critical FPGA elements: LUT-based logic, distributed and embedded memory, PLLs and support for mainstream I/Os. Dedicated DDR memory interface logic is also included to support this memory that is becoming increasingly prevalent in cost-sensitive applications.

The ispLEVER® design tool suite from Lattice allows large complex designs to be efficiently implemented using the LatticeECP/EC FPGA family. Synthesis library support for LatticeECP/EC is available for popular logic synthesis tools. The ispLEVER tool uses the synthesis tool output along with the constraints from its floor planning tools to place and route the design in the LatticeECP/EC device. The ispLEVER tool extracts the timing from the routing and back-annotates it into the design for timing verification.

Lattice provides many pre-designed IP (Intellectual Property) ispLeverCORE™ modules for the LatticeECP/EC family. By using these IPs as standardized blocks, designers are free to concentrate on the unique aspects of their design, increasing their productivity.

September 2012

Data Sheet

Architecture Overview

The LatticeECP-DSP and LatticeEC architectures contain an array of logic blocks surrounded by Programmable I/O Cells (PIC). Interspersed between the rows of logic blocks are rows of sysMEM Embedded Block RAM (EBR), as shown in Figures 2-1 and 2-2. In addition, LatticeECP-DSP supports an additional row of DSP blocks, as shown in Figure 2-2.

There are two kinds of logic blocks, the Programmable Functional Unit (PFU) and Programmable Functional unit without RAM/ROM (PFF). The PFU contains the building blocks for logic, arithmetic, RAM, ROM and register functions. The PFF block contains building blocks for logic, arithmetic and ROM functions. Both PFU and PFF blocks are optimized for flexibility, allowing complex designs to be implemented quickly and efficiently. Logic Blocks are arranged in a two-dimensional array. Only one type of block is used per row. The PFU blocks are used on the outside rows. The rest of the core consists of rows of PFF blocks interspersed with rows of PFU blocks. For every three rows of PFF blocks there is a row of PFU blocks.

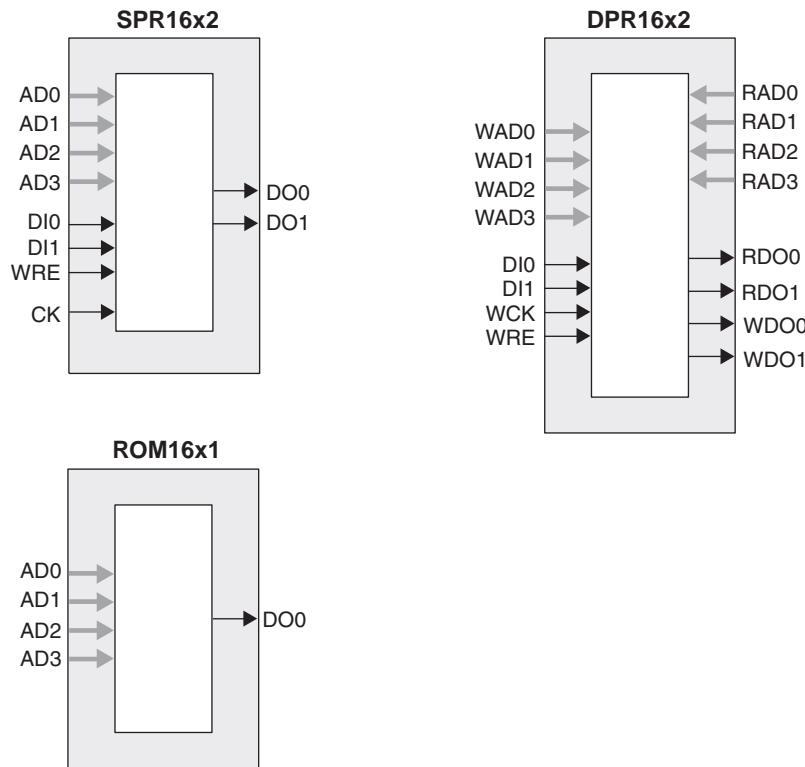
Each PIC block encompasses two PIOs (PIO pairs) with their respective sysI/O interfaces. PIO pairs on the left and right edges of the device can be configured as LVDS transmit/receive pairs. sysMEM EBRs are large dedicated fast memory blocks. They can be configured as RAM or ROM.

The PFU, PFF, PIC and EBR Blocks are arranged in a two-dimensional grid with rows and columns as shown in Figure 2-1. The blocks are connected with many vertical and horizontal routing channel resources. The place and route software tool automatically allocates these routing resources.

At the end of the rows containing the sysMEM Blocks are the sysCLOCK Phase Locked Loop (PLL) Blocks. These PLLs have multiply, divide and phase shifting capability; they are used to manage the phase relationship of the clocks. The LatticeECP/EC architecture provides up to four PLLs per device.

Every device in the family has a JTAG Port with internal Logic Analyzer (ispTRACY) capability. The sysCONFIG™ port which allows for serial or parallel device configuration. The LatticeECP/EC devices use 1.2V as their core voltage.

Figure 2-5. Distributed Memory Primitives



ROM Mode: The ROM mode uses the same principal as the RAM modes, but without the Write port. Pre-loading is accomplished through the programming interface during configuration.

PFU Modes of Operation

Slices can be combined within a PFU to form larger functions. Table 2-4 tabulates these modes and documents the functionality possible at the PFU level.

Table 2-4. PFU Modes of Operation

Logic	Ripple	RAM ¹	ROM
LUT 4x8 or MUX 2x1 x 8	2-bit Add x 4	SPR16x2 x 4 DPR16x2 x 2	ROM16x1 x 8
LUT 5x4 or MUX 4x1 x 4	2-bit Sub x 4	SPR16x4 x 2 DPR16x4 x 1	ROM16x2 x 4
LUT 6x 2 or MUX 8x1 x 2	2-bit Counter x 4	SPR16x8 x 1	ROM16x4 x 2
LUT 7x1 or MUX 16x1 x 1	2-bit Comp x 4		ROM16x8 x 1

1. These modes are not available in PFF blocks

IPexpress™

The user can access the sysDSP block via the IPexpress configuration tool, included with the ispLEVER design tool suite. IPexpress has options to configure each DSP module (or group of modules) or through direct HDL instantiation. Additionally Lattice has partnered Mathworks to support instantiation in the Simulink tool, which is a Graphical Simulation Environment. Simulink works with ispLEVER and dramatically shortens the DSP design cycle in Lattice FPGAs.

Optimized DSP Functions

Lattice provides a library of optimized DSP IP functions. Some of the IPs planned for LatticeECP DSP are: Bit Correlators, Fast Fourier Transform, Finite Impulse Response (FIR) Filter, Reed-Solomon Encoder/ Decoder, Turbo Encoder/Decoders and Convolutional Encoder/Decoder. Please contact Lattice to obtain the latest list of available DSP IPs.

Resources Available in the LatticeECP Family

Table 2-9 shows the maximum number of multipliers for each member of the LatticeECP family. Table 2-10 shows the maximum available EBR RAM Blocks in each of the LatticeECP family. EBR blocks, together with Distributed RAM can be used to store variables locally for the fast DSP operations.

Table 2-9. Number of DSP Blocks in LatticeECP Family

Device	DSP Block	9x9 Multiplier	18x18 Multiplier	36x36 Multiplier
LFECP6	4	32	16	4
LFECP10	5	40	20	5
LFECP15	6	48	24	6
LFECP20	7	56	28	7
LFECP33	8	64	32	8

Table 2-10. Embedded SRAM in LatticeECP Family

Device	EBR SRAM Block	Total EBR SRAM (Kbits)
LFECP6	10	92
LFECP10	30	276
LFECP15	38	350
LFECP20	46	424
LFECP33	54	498

DSP Performance of the LatticeECP Family

Table 2-11 lists the maximum performance in millions of MAC operations per second (MMAC) for each member of the LatticeECP family.

Table 2-11. DSP Block Performance of LatticeECP Family

Device	DSP Block	DSP Performance MMAC
LFECP6	4	3680
LFECP10	5	4600
LFECP15	6	5520
LFECP20	7	6440
LFECP33	8	7360

Input Register Block

The input register block contains delay elements and registers that can be used to condition signals before they are passed to the device core. Figure 2-26 shows the diagram of the input register block.

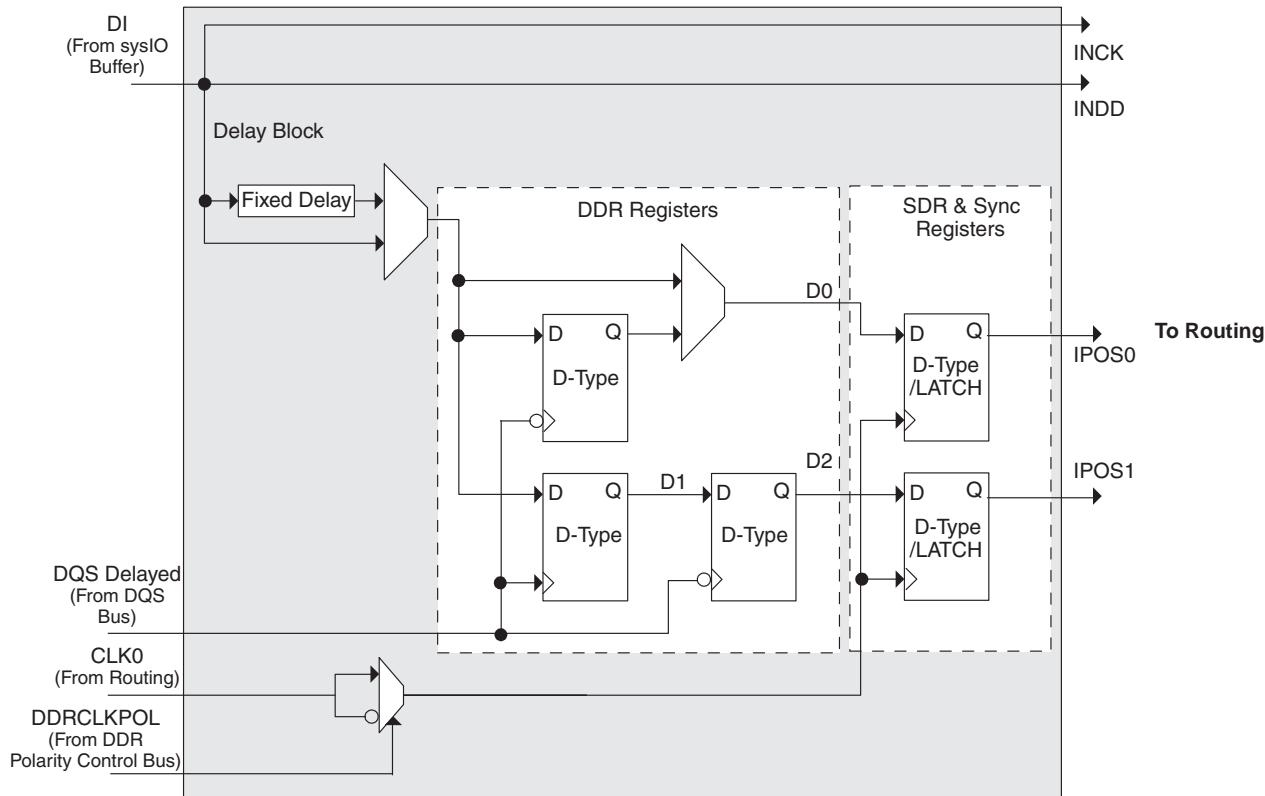
Input signals are fed from the sysI/O buffer to the input register block (as signal DI). If desired the input signal can bypass the register and delay elements and be used directly as a combinatorial signal (INDD), a clock (INCK) and in selected blocks the input to the DQS delay block. If one of the bypass options is not chosen, the signal first passes through an optional delay block. This delay, if selected, reduces input-register hold-time requirement when using a global clock.

The input block allows two modes of operation. In the single data rate (SDR) the data is registered, by one of the registers in the single data rate sync register block, with the system clock. In the DDR Mode two registers are used to sample the data on the positive and negative edges of the DQS signal creating two data streams, D0 and D2. These two data streams are synchronized with the system clock before entering the core. Further discussion on this topic is in the DDR Memory section of this data sheet.

Figure 2-27 shows the input register waveforms for DDR operation and Figure 2-28 shows the design tool primitives. The SDR/SYNC registers have reset and clock enable available.

The signal DDRCLKPOL controls the polarity of the clock used in the synchronization registers. It ensures adequate timing when data is transferred from the DQS to system clock domain. For further discussion on this topic, see the DDR Memory section of this data sheet.

Figure 2-26. Input Register Diagram



DC Electrical Characteristics

Over Recommended Operating Conditions

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
I_{IL}, I_{IH}^1	Input or I/O Leakage	$0 \leq V_{IN} \leq (V_{CCIO} - 0.2V)$	—	—	10	μA
$I_{IH}^{1,3}$	Input or I/O High Leakage	$(V_{CCIO} - 0.2V) \leq V_{IH} \leq 3.6V$	—	—	40	μA
I_{PU}	I/O Active Pull-up Current	$0 \leq V_{IN} \leq 0.7 V_{CCIO}$	-30	—	-150	μA
I_{PD}	I/O Active Pull-down Current	$V_{IL}(\text{MAX}) \leq V_{IN} \leq V_{IH}(\text{MAX})$	30	—	150	μA
I_{BHLs}	Bus Hold Low sustaining current	$V_{IN} = V_{IL}(\text{MAX})$	30	—	—	μA
I_{BHHS}	Bus Hold High sustaining current	$V_{IN} = 0.7V_{CCIO}$	-30	—	—	μA
I_{BHLO}	Bus Hold Low Overdrive current	$0 \leq V_{IN} \leq V_{IH}(\text{MAX})$	—	—	150	μA
I_{BHLH}	Bus Hold High Overdrive current	$0 \leq V_{IN} \leq V_{IH}(\text{MAX})$	—	—	-150	μA
V_{BHT}	Bus Hold trip Points	$0 \leq V_{IN} \leq V_{IH}(\text{MAX})$	$V_{IL}(\text{MAX})$	—	$V_{IH}(\text{MIN})$	V
C1	I/O Capacitance ²	$V_{CCIO} = 3.3V, 2.5V, 1.8V, 1.5V, 1.2V$, $V_{CC} = 1.2V$, $V_{IO} = 0$ to $V_{IH}(\text{MAX})$	—	8	—	pf
C2	Dedicated Input Capacitance ²	$V_{CCIO} = 3.3V, 2.5V, 1.8V, 1.5V, 1.2V$, $V_{CC} = 1.2V$, $V_{IO} = 0$ to $V_{IH}(\text{MAX})$	—	6	—	pf

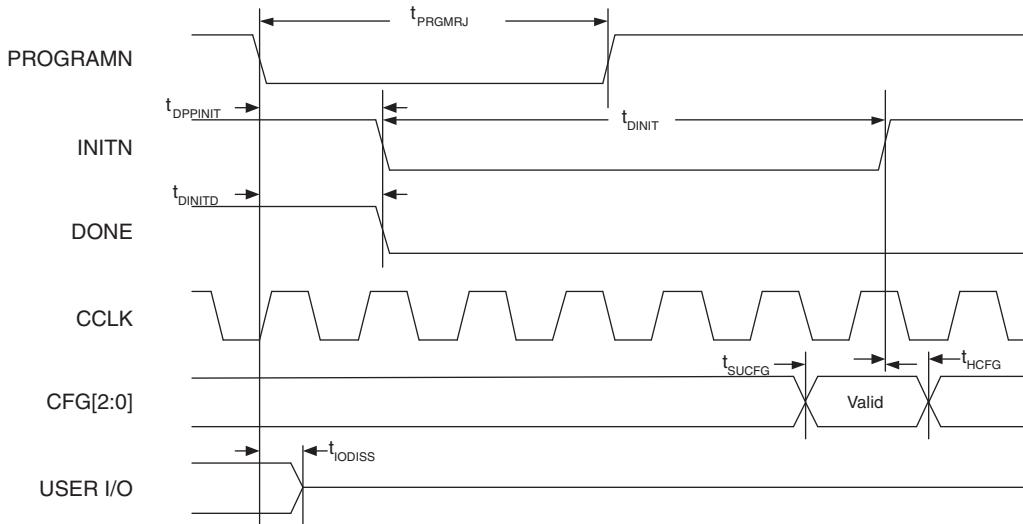
1. Input or I/O leakage current is measured with the pin configured as an input or as an I/O with the output driver tri-stated. It is not measured with the output driver active. Bus maintenance circuits are disabled.
2. $T_A = 25^\circ C$, $f = 1.0\text{MHz}$
3. For top and bottom general purpose I/O pins, when V_{IH} is higher than V_{CCIO} , a transient current typically of 30ns in duration or less with a peak current of 6mA can occur on the high-to-low transition. For left and right I/O banks, V_{IH} must be less than or equal to V_{CCIO} .

LatticeECP/EC External Switching Characteristics

Over Recommended Operating Conditions

Parameter	Description	Device	-5		-4		-3		Units
			Min.	Max.	Min.	Max.	Min.	Max.	
General I/O Pin Parameters (Using Primary Clock without PLL)¹									
t_{CO}^7	Clock to Output - PIO Output Register	LFEC1	—	5.09	—	6.11	—	7.13	ns
		LFEC3	—	5.71	—	6.85	—	7.99	ns
		LFEC6	—	5.60	—	6.72	—	7.84	ns
		LFEC10	—	5.47	—	6.57	—	7.66	ns
		LFEC15	—	5.67	—	6.81	—	7.94	ns
		LFEC20	—	5.89	—	7.07	—	8.25	ns
		LFEC33	—	6.19	—	7.42	—	8.66	ns
t_{SU}^7	Clock to Data Setup - PIO Input Register	LFEC1	-0.08	—	-0.10	—	-0.12	—	ns
		LFEC3	-0.70	—	-0.84	—	-0.98	—	ns
		LFEC6	-0.63	—	-0.76	—	-0.89	—	ns
		LFEC10	-0.43	—	-0.52	—	-0.61	—	ns
		LFEC15	-0.70	—	-0.84	—	-0.98	—	ns
		LFEC20	-0.88	—	-1.06	—	-1.24	—	ns
		LFEC33	-1.12	—	-1.34	—	-1.56	—	ns
t_H^7	Clock to Data Hold - PIO Input Register	LFEC1	2.19	—	2.62	—	3.06	—	ns
		LFEC3	2.80	—	3.36	—	3.92	—	ns
		LFEC6	2.69	—	3.23	—	3.77	—	ns
		LFEC10	2.56	—	3.08	—	3.59	—	ns
		LFEC15	2.76	—	3.32	—	3.87	—	ns
		LFEC20	2.99	—	3.58	—	4.18	—	ns
		LFEC33	3.28	—	3.93	—	4.59	—	ns
$t_{SU_DEL}^7$	Clock to Data Setup - PIO Input Register with Data Input Delay	LFEC1	3.36	—	4.03	—	4.70	—	ns
		LFEC3	2.74	—	3.29	—	3.84	—	ns
		LFEC6	2.81	—	3.37	—	3.93	—	ns
		LFEC10	3.01	—	3.61	—	4.21	—	ns
		LFEC15	2.74	—	3.29	—	3.83	—	ns
		LFEC20	2.56	—	3.07	—	3.58	—	ns
		LFEC33	2.32	—	2.79	—	3.25	—	ns
$t_{H_DEL}^7$	Clock to Data Hold - PIO Input Register with Input Data Delay	LFEC1	-1.31	—	-1.57	—	-1.83	—	ns
		LFEC3	-0.70	—	-0.83	—	-0.97	—	ns
		LFEC6	-0.80	—	-0.96	—	-1.12	—	ns
		LFEC10	-0.93	—	-1.12	—	-1.30	—	ns
		LFEC15	-0.73	—	-0.88	—	-1.02	—	ns
		LFEC20	-0.51	—	-0.61	—	-0.71	—	ns
		LFEC33	-0.22	—	-0.26	—	-0.30	—	ns
$f_{MAX_IO}^2$	Clock Frequency of I/O and PFU Register	All	—	420	—	378	—	340	Mhz
DDR I/O Pin Parameters^{3, 4, 5}									
t_{DVADQ}	Data Valid After DQS (DDR Read)	All	—	0.19	—	0.19	—	0.19	UI
t_{DVEDQ}	Data Hold After DQS (DDR Read)	All	0.67	—	0.67	—	0.67	—	UI

Figure 3-17. Configuration from PROGRAMN Timing



1. The CFG pins are normally static (hard wired)

Figure 3-18. Wake-Up Timing

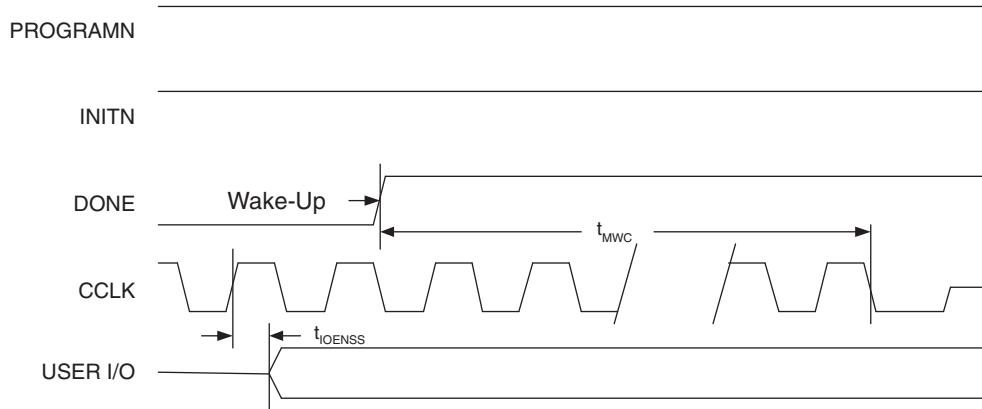
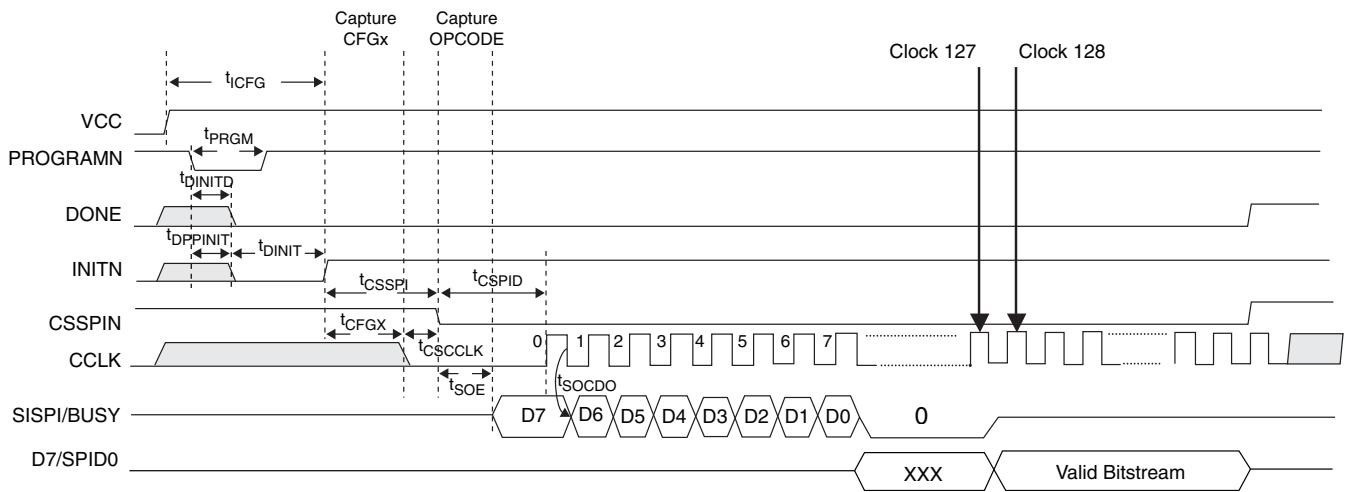


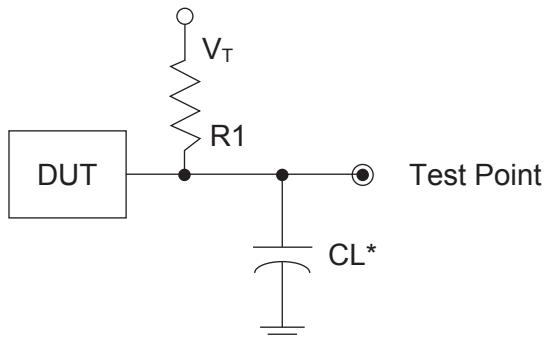
Figure 3-19. sysCONFIG SPI Port Sequence



Switching Test Conditions

Figure 3-21 shows the output test load that is used for AC testing. The specific values for resistance, capacitance, voltage, and other test conditions are shown in Table 3-6.

Figure 3-21. Output Test Load, LVTTL and LVC MOS Standards



*CL Includes Test Fixture and Probe Capacitance

Table 3-6. Test Fixture Required Components, Non-Terminated Interfaces

Test Condition	R ₁	C _L	Timing Ref.	V _T
LVTTL and other LVC MOS settings (L -> H, H -> L)	∞	0pF	LVC MOS 3.3 = 1.5V	—
			LVC MOS 2.5 = V _{CCIO} /2	—
			LVC MOS 1.8 = V _{CCIO} /2	—
			LVC MOS 1.5 = V _{CCIO} /2	—
			LVC MOS 1.2 = V _{CCIO} /2	—
LVC MOS 2.5 I/O (Z -> H)	188 $\frac{3}{4}$	0pF	V _{CCIO} /2	V _{OL}
LVC MOS 2.5 I/O (Z -> L)			V _{CCIO} /2	V _{OH}
LVC MOS 2.5 I/O (H -> Z)			V _{OH} - 0.15	V _{OL}
LVC MOS 2.5 I/O (L -> Z)			V _{OL} + 0.15	V _{OH}

Note: Output test conditions for all other interfaces are determined by the respective standards.

Signal Descriptions (Cont.)

Signal Name	I/O	Description
TDI	I	Test Data in pin. Used to load data into device using 1149.1 state machine. After power-up, this TAP port can be activated for configuration by sending appropriate command. (Note: once a configuration port is selected it is locked. Another configuration port cannot be selected until the power-up sequence). Pull-up is enabled during configuration.
TDO	O	Output pin. Test Data out pin used to shift data out of device using 1149.1.
V _{CCJ}	—	V _{CCJ} - The power supply pin for JTAG Test Access Port.
Configuration Pads (used during sysCONFIG)		
CFG[2:0]	I	Mode pins used to specify configuration modes values latched on rising edge of INITN. During configuration, a pull-up is enabled. These are dedicated pins.
INITN	I/O	Open Drain pin. Indicates the FPGA is ready to be configured. During configuration, a pull-up is enabled. It is a dedicated pin.
PROGRAMN	I	Initiates configuration sequence when asserted low. This pin always has an active pull-up. This is a dedicated pin.
DONE	I/O	Open Drain pin. Indicates that the configuration sequence is complete, and the startup sequence is in progress. This is a dedicated pin.
CCLK	I/O	Configuration Clock for configuring an FPGA in sysCONFIG mode.
BUSY/SISPI	I/O	Read control command in SPI3 or SPIX mode.
CSN	I	sysCONFIG chip select (Active low). During configuration, a pull-up is enabled.
CS1N	I	sysCONFIG chip select (Active low). During configuration, a pull-up is enabled.
WRITEN	I	Write Data on Parallel port (Active low).
D[7:0]/SPID[0:7]	I/O	sysCONFIG Port Data I/O.
DOUT/CSON	O	Output for serial configuration data (rising edge of CCLK) when using sysCONFIG port.
DI/CSSPIN	I/O	Input for serial configuration data (clocked with CCLK) when using sysCONFIG port. During configuration, a pull-up is enabled. Output when used in SPI/SPIX modes.

Pin Information Summary (Cont.)

		LFECP/EC15	LFECP20/EC20		LFECP/EC33		
Pin Type		256-fpBGA	484-fpBGA	484-fpBGA	672-fpBGA	484-fpBGA	672-fpBGA
Single Ended User I/O		195	352	360	400	360	496
Differential Pair User I/O		97	176	180	200	180	248
Configuration	Dedicated	13	13	13	13	13	13
	Muxed	56	56	56	56	56	56
TAP		5	5	5	5	5	5
Dedicated (total without supplies)		208	373	373	509	373	509
V _{CC}		10	20	20	32	16	28
V _{CCAUX}		2	12	12	20	12	20
V _{CCPLL}		0	0	0	0	4	4
V _{CCIO}	Bank0	2	4	4	6	4	6
	Bank1	2	4	4	6	4	6
	Bank2	2	4	4	6	4	6
	Bank3	2	4	4	6	4	6
	Bank4	2	4	4	6	4	6
	Bank5	2	4	4	6	4	6
	Bank6	2	4	4	6	4	6
	Bank7	2	4	4	6	4	6
GND, GND0-GND7		20	44	44	63	44	63
NC		0	11	3	96	3	0
Single Ended/ Differential I/O Pair per Bank	Bank0	32/16	48/24	48/24	64/32	48/24	64/32
	Bank1	18/9	48/24	48/24	48/24	48/24	64/32
	Bank2	16/8	40/20	40/20	40/20	40/20	56/28
	Bank3	32/16	40/20	44/22	48/24	44/22	64/32
	Bank4	17/8	48/24	48/24	48/24	48/24	64/32
	Bank5	32/16	48/24	48/24	64/32	48/24	64/32
	Bank6	32/16	40/20	44/22	48/24	44/22	64/32
	Bank7	16/8	40/20	40/20	40/20	40/20	56/28
V _{CCJ}		1	1	1	1	1	1

Note: During configuration the user-programmable I/Os are tri-stated with an internal pull-up resistor enabled. If any pin is not used (or not bonded to a package pin), it is also tri-stated with an internal pull-up resistor enabled after configuration.

LFEC1, LFEC3 Logic Signal Connections: 208 PQFP (Cont.)

Pin Number	LFEC1				LFEC3			
	Pin Function	Bank	LVDS	Dual Function	Pin Function	Bank	LVDS	Dual Function
43	PL11A	6	T	LDQS11	PL15A	6	T	LDQS15
44	PL11B	6	C		PL15B	6	C	
45	PL12A	6	T		PL16A	6	T	
46	PL12B	6	C		PL16B	6	C	
47	PL13A	6	T		PL17A	6	T	
48	PL13B	6	C		PL17B	6	C	
49	PL14A	6	T	VREF1_6	PL18A	6	T	VREF1_6
50	PL14B	6	C	VREF2_6	PL18B	6	C	VREF2_6
51	VCCIO6	6			VCCIO6	6		
52*	GND5 GND6	-			GND5 GND6	-		
53	VCCIO5	5			VCCIO5	5		
54	NC	-			PB2A	5	T	
55	NC	-			PB2B	5	C	
56	NC	-			PB3A	5	T	
57	NC	-			PB3B	5	C	
58	NC	-			PB4A	5	T	
59	NC	-			PB4B	5	C	
60	NC	-			PB5A	5	T	
61	NC	-			PB5B	5	C	
62	NC	-			PB6A	5	T	BDQS6
63	NC	-			PB6B	5	C	
64	NC	-			VCCIO5	5		
65	PB2A	5	T		PB10A	5	T	
66	PB2B	5	C		PB10B	5	C	
67	PB3A	5	T		PB11A	5	T	
68	PB3B	5	C		PB11B	5	C	
69	PB4A	5	T		PB12A	5	T	
70	PB4B	5	C		PB12B	5	C	
71	PB5A	5	T		PB13A	5	T	
72	NC	-			GND5	5		
73	PB5B	5	C		PB13B	5	C	
74	VCCIO5	5			VCCIO5	5		
75	PB6A	5	T	BDQS6	PB14A	5	T	BDQS14
76	PB6B	5	C		PB14B	5	C	
77	PB7A	5	T		PB15A	5	T	
78	PB7B	5	C		PB15B	5	C	
79	PB8A	5	T	VREF2_5	PB16A	5	T	VREF2_5
80	PB8B	5	C	VREF1_5	PB16B	5	C	VREF1_5
81	PB9A	5	T	PCLKT5_0	PB17A	5	T	PCLKT5_0
82	GND5	5			GND5	5		
83	PB9B	5	C	PCLKC5_0	PB17B	5	C	PCLKC5_0
84	VCCAUX	-			VCCAUX	-		

LFEC1, LFEC3 Logic Signal Connections: 208 PQFP (Cont.)

Pin Number	LFEC1				LFEC3			
	Pin Function	Bank	LVDS	Dual Function	Pin Function	Bank	LVDS	Dual Function
169	PT13A	1	T		PT21A	1	T	
170	PT12B	1	C		PT20B	1	C	
171	PT12A	1	T		PT20A	1	T	
172	PT11B	1	C	VREF2_1	PT19B	1	C	VREF2_1
173	PT11A	1	T	VREF1_1	PT19A	1	T	VREF1_1
174	PT10B	1	C		PT18B	1	C	
175	PT10A	1	T		PT18A	1	T	
176	VCCIO1	1			VCCIO1	1		
177	VCCAUX	-			VCCAUX	-		
178	PT9B	0	C	PCLKC0_0	PT17B	0	C	PCLKC0_0
179	GND0	0			GND0	0		
180	PT9A	0	T	PCLKT0_0	PT17A	0	T	PCLKT0_0
181	PT8B	0	C	VREF1_0	PT16B	0	C	VREF1_0
182	PT8A	0	T	VREF2_0	PT16A	0	T	VREF2_0
183	PT7B	0	C		PT15B	0	C	
184	PT7A	0	T		PT15A	0	T	
185	PT6B	0	C		PT14B	0	C	
186	PT6A	0	T	TDQS6	PT14A	0	T	TDQS14
187	VCCIO0	0			VCCIO0	0		
188	PT5B	0	C		PT13B	0	C	
189	NC	-			GND0	0		
190	PT5A	0	T		PT13A	0	T	
191	PT4B	0	C		PT12B	0	C	
192	PT4A	0	T		PT12A	0	T	
193	PT3B	0	C		PT11B	0	C	
194	PT3A	0	T		PT11A	0	T	
195	PT2B	0	C		PT10B	0	C	
196	PT2A	0	T		PT10A	0	T	
197	NC	-			VCCIO0	0		
198	NC	-			PT6B	0	C	
199	NC	-			PT6A	0	T	TDQS6
200	NC	-			PT5B	0	C	
201	NC	-			PT5A	0	T	
202	NC	-			PT4B	0	C	
203	NC	-			PT4A	0	T	
204	NC	-			PT3B	0	C	
205	NC	-			PT3A	0	T	
206	NC	-			PT2B	0	C	
207	NC	-			PT2A	0	T	
208	VCCIO0	0			VCCIO0	0		

* Double bonded to the pin.

LFEC3 and LFECP/EC6 Logic Signal Connections: 256 fpBGA (Cont.)

Ball Number	LFEC3				LFECP6/LFEC6			
	Ball Function	Bank	LVDS	Dual Function	Ball Function	Bank	LVDS	Dual Function
D7	PT11B	0	C		PT11B	0	C	
C7	PT11A	0	T		PT11A	0	T	
A7	PT10B	0	C		PT10B	0	C	
A6	PT10A	0	T		PT10A	0	T	
E7	PT9B	0	C		PT9B	0	C	
GND	GND0	0			GND0	0		
E6	PT9A	0	T		PT9A	0	T	
D6	PT8B	0	C		PT8B	0	C	
C6	PT8A	0	T		PT8A	0	T	
B6	PT7B	0	C		PT7B	0	C	
B5	PT7A	0	T		PT7A	0	T	
A5	PT6B	0	C		PT6B	0	C	
A4	PT6A	0	T	TDQS6	PT6A	0	T	TDQS6
A3	PT5B	0	C		PT5B	0	C	
A2	PT5A	0	T		PT5A	0	T	
B2	PT4B	0	C		PT4B	0	C	
B3	PT4A	0	T		PT4A	0	T	
D5	PT3B	0	C		PT3B	0	C	
C5	PT3A	0	T		PT3A	0	T	
C4	PT2B	0	C		PT2B	0	C	
B4	PT2A	0	T		PT2A	0	T	
GND	GND0	0			GND0	0		
A1	GND	-			GND	-		
A16	GND	-			GND	-		
G10	GND	-			GND	-		
G7	GND	-			GND	-		
G8	GND	-			GND	-		
G9	GND	-			GND	-		
H10	GND	-			GND	-		
H7	GND	-			GND	-		
H8	GND	-			GND	-		
H9	GND	-			GND	-		
J10	GND	-			GND	-		
J7	GND	-			GND	-		
J8	GND	-			GND	-		
J9	GND	-			GND	-		
K10	GND	-			GND	-		
K7	GND	-			GND	-		
K8	GND	-			GND	-		
K9	GND	-			GND	-		
T1	GND	-			GND	-		
T16	GND	-			GND	-		
E12	VCC	-			VCC	-		

LFECP/EC20, LFECP/EC33 Logic Signal Connections: 672 fpBGA (Cont.)

LFECP20/LFECP20					LFECP/EC33				
Ball Number	Ball Function	Bank	LVDS	Dual Function	Ball Number	Ball Function	Bank	LVDS	Dual Function
J14	VCCIO1	1			J14	VCCIO1	1		
J15	VCCIO1	1			J15	VCCIO1	1		
J16	VCCIO1	1			J16	VCCIO1	1		
J17	VCCIO1	1			J17	VCCIO1	1		
K17	VCCIO2	2			K17	VCCIO2	2		
K18	VCCIO2	2			K18	VCCIO2	2		
L18	VCCIO2	2			L18	VCCIO2	2		
M18	VCCIO2	2			M18	VCCIO2	2		
N18	VCCIO2	2			N18	VCCIO2	2		
N19	VCCIO2	2			N19	VCCIO2	2		
P18	VCCIO3	3			P18	VCCIO3	3		
P19	VCCIO3	3			P19	VCCIO3	3		
R18	VCCIO3	3			R18	VCCIO3	3		
R19	VCCIO3	3			R19	VCCIO3	3		
T18	VCCIO3	3			T18	VCCIO3	3		
U18	VCCIO3	3			U18	VCCIO3	3		
V14	VCCIO4	4			V14	VCCIO4	4		
V15	VCCIO4	4			V15	VCCIO4	4		
V16	VCCIO4	4			V16	VCCIO4	4		
V17	VCCIO4	4			V17	VCCIO4	4		
W14	VCCIO4	4			W14	VCCIO4	4		
W15	VCCIO4	4			W15	VCCIO4	4		
V10	VCCIO5	5			V10	VCCIO5	5		
V11	VCCIO5	5			V11	VCCIO5	5		
V12	VCCIO5	5			V12	VCCIO5	5		
V13	VCCIO5	5			V13	VCCIO5	5		
W12	VCCIO5	5			W12	VCCIO5	5		
W13	VCCIO5	5			W13	VCCIO5	5		
P8	VCCIO6	6			P8	VCCIO6	6		
P9	VCCIO6	6			P9	VCCIO6	6		
R8	VCCIO6	6			R8	VCCIO6	6		
R9	VCCIO6	6			R9	VCCIO6	6		
T9	VCCIO6	6			T9	VCCIO6	6		
U9	VCCIO6	6			U9	VCCIO6	6		
K9	VCCIO7	7			K9	VCCIO7	7		
L9	VCCIO7	7			L9	VCCIO7	7		
M8	VCCIO7	7			M8	VCCIO7	7		
M9	VCCIO7	7			M9	VCCIO7	7		
N8	VCCIO7	7			N8	VCCIO7	7		
N9	VCCIO7	7			N9	VCCIO7	7		
G13	VCCAUX	-			G13	VCCAUX	-		
H20	VCCAUX	-			H20	VCCAUX	-		

Conventional Packaging

LatticeEC Commercial

Part Number	I/Os	Grade	Package	Pins	Temp.	LUTs
LFEC1E-3Q208C	112	-3	PQFP	208	COM	1.5K
LFEC1E-4Q208C	112	-4	PQFP	208	COM	1.5K
LFEC1E-5Q208C	112	-5	PQFP	208	COM	1.5K
LFEC1E-3T144C	97	-3	TQFP	144	COM	1.5K
LFEC1E-4T144C	97	-4	TQFP	144	COM	1.5K
LFEC1E-5T144C	97	-5	TQFP	144	COM	1.5K
LFEC1E-3T100C	67	-3	TQFP	100	COM	1.5K
LFEC1E-4T100C	67	-4	TQFP	100	COM	1.5K
LFEC1E-5T100C	67	-5	TQFP	100	COM	1.5K

Part Number	I/Os	Grade	Package	Pins	Temp.	LUTs
LFEC3E-3F256C	160	-3	fpBGA	256	COM	3.1K
LFEC3E-4F256C	160	-4	fpBGA	256	COM	3.1K
LFEC3E-5F256C	160	-5	fpBGA	256	COM	3.1K
LFEC3E-3Q208C	145	-3	PQFP	208	COM	3.1K
LFEC3E-4Q208C	145	-4	PQFP	208	COM	3.1K
LFEC3E-5Q208C	145	-5	PQFP	208	COM	3.1K
LFEC3E-3T144C	97	-3	TQFP	144	COM	3.1K
LFEC3E-4T144C	97	-4	TQFP	144	COM	3.1K
LFEC3E-5T144C	97	-5	TQFP	144	COM	3.1K
LFEC3E-3T100C	67	-3	TQFP	100	COM	3.1K
LFEC3E-4T100C	67	-4	TQFP	100	COM	3.1K
LFEC3E-5T100C	67	-5	TQFP	100	COM	3.1K

Part Number	I/Os	Grade	Package	Pins	Temp.	LUTs
LFEC6E-3F484C	224	-3	fpBGA	484	COM	6.1K
LFEC6E-4F484C	224	-4	fpBGA	484	COM	6.1K
LFEC6E-5F484C	224	-5	fpBGA	484	COM	6.1K
LFEC6E-3F256C	195	-3	fpBGA	256	COM	6.1K
LFEC6E-4F256C	195	-4	fpBGA	256	COM	6.1K
LFEC6E-5F256C	195	-5	fpBGA	256	COM	6.1K
LFEC6E-3Q208C	147	-3	PQFP	208	COM	6.1K
LFEC6E-4Q208C	147	-4	PQFP	208	COM	6.1K
LFEC6E-5Q208C	147	-5	PQFP	208	COM	6.1K
LFEC6E-3T144C	97	-3	TQFP	144	COM	6.1K
LFEC6E-4T144C	97	-4	TQFP	144	COM	6.1K
LFEC6E-5T144C	97	-5	TQFP	144	COM	6.1K

Part Number	I/Os	Grade	Package	Pins	Temp.	LUTs
LFEC10E-3F484C	288	-3	fpBGA	484	COM	10.2K
LFEC10E-4F484C	288	-4	fpBGA	484	COM	10.2K
LFEC10E-5F484C	288	-5	fpBGA	484	COM	10.2K
LFEC10E-3F256C	195	-3	fpBGA	256	COM	10.2K

LatticeECP Commercial

Part Number	I/Os	Grade	Package	Pins	Temp.	LUTs
LFECP6E-3F484C	224	-3	fpBGA	484	COM	6.1K
LFECP6E-4F484C	224	-4	fpBGA	484	COM	6.1K
LFECP6E-5F484C	224	-5	fpBGA	484	COM	6.1K
LFECP6E-3F256C	195	-3	fpBGA	256	COM	6.1K
LFECP6E-4F256C	195	-4	fpBGA	256	COM	6.1K
LFECP6E-5F256C	195	-5	fpBGA	256	COM	6.1K
LFECP6E-3Q208C	147	-3	PQFP	208	COM	6.1K
LFECP6E-4Q208C	147	-4	PQFP	208	COM	6.1K
LFECP6E-5Q208C	147	-5	PQFP	208	COM	6.1K
LFECP6E-3T144C	97	-3	TQFP	144	COM	6.1K
LFECP6E-4T144C	97	-4	TQFP	144	COM	6.1K
LFECP6E-5T144C	97	-5	TQFP	144	COM	6.1K

Part Number	I/Os	Grade	Package	Pins	Temp.	LUTs
LFECP10E-3F484C	288	-3	fpBGA	484	COM	10.2K
LFECP10E-4F484C	288	-4	fpBGA	484	COM	10.2K
LFECP10E-5F484C	288	-5	fpBGA	484	COM	10.2K
LFECP10E-3F256C	195	-3	fpBGA	256	COM	10.2K
LFECP10E-4F256C	195	-4	fpBGA	256	COM	10.2K
LFECP10E-5F256C	195	-5	fpBGA	256	COM	10.2K
LFECP10E-3Q208C	147	-3	PQFP	208	COM	10.2K
LFECP10E-4Q208C	147	-4	PQFP	208	COM	10.2K
LFECP10E-5Q208C	147	-5	PQFP	208	COM	10.2K

Part Number	I/Os	Grade	Package	Pins	Temp.	LUTs
LFECP15E-3F484C	352	-3	fpBGA	484	COM	15.3K
LFECP15E-4F484C	352	-4	fpBGA	484	COM	15.3K
LFECP15E-5F484C	352	-5	fpBGA	484	COM	15.3K
LFECP15E-3F256C	195	-3	fpBGA	256	COM	15.3K
LFECP15E-4F256C	195	-4	fpBGA	256	COM	15.3K
LFECP15E-5F256C	195	-5	fpBGA	256	COM	15.3K

Part Number	I/Os	Grade	Package	Pins	Temp.	LUTs
LFECP20E-3F672C	400	-3	fpBGA	672	COM	19.7K
LFECP20E-4F672C	400	-4	fpBGA	672	COM	19.7K
LFECP20E-5F672C	400	-5	fpBGA	672	COM	19.7K
LFECP20E-3F484C	360	-3	fpBGA	484	COM	19.7K
LFECP20E-4F484C	360	-4	fpBGA	484	COM	19.7K
LFECP20E-5F484C	360	-5	fpBGA	484	COM	19.7K

Part Number	I/Os	Grade	Package	Pins	Temp.	LUTs
LFECP33E-3F672C	496	-3	fpBGA	672	COM	32.8K
LFECP33E-4F672C	496	-4	fpBGA	672	COM	32.8K
LFECP33E-5F672C	496	-5	fpBGA	672	COM	32.8K



Ordering Information
LatticeECP/EC Family Data Sheet

LatticeEC Industrial (Continued)

Part Number	I/Os	Grade	Package	Pins	Temp.	LUTs
LFEC15E-3F484I	352	-3	fpBGA	484	IND	15.3K
LFEC15E-4F484I	352	-4	fpBGA	484	IND	15.3K
LFEC15E-3F256I	195	-3	fpBGA	256	IND	15.3K
LFEC15E-4F256I	195	-4	fpBGA	256	IND	15.3K

Part Number	I/Os	Grade	Package	Pins	Temp.	LUTs
LFEC20E-3F672I	400	-3	fpBGA	672	IND	19.7K
LFEC20E-4F672I	400	-4	fpBGA	672	IND	19.7K
LFEC20E-3F484I	360	-3	fpBGA	484	IND	19.7K
LFEC20E-4F484I	360	-4	fpBGA	484	IND	19.7K

Part Number	I/Os	Grade	Package	Pins	Temp.	LUTs
LFEC33E-3F672I	496	-3	fpBGA	672	IND	32.8
LFEC33E-4F672I	496	-4	fpBGA	672	IND	32.8
LFEC33E-3F484I	360	-3	fpBGA	484	IND	32.8
LFEC33E-4F484I	360	-4	fpBGA	484	IND	32.8

LatticeECP Industrial

Part Number	I/Os	Grade	Package	Pins	Temp.	LUTs
LFECP6E-3F484I	224	-3	fpBGA	484	IND	6.1K
LFECP6E-4F484I	224	-4	fpBGA	484	IND	6.1K
LFECP6E-3F256I	195	-3	fpBGA	256	IND	6.1K
LFECP6E-4F256I	195	-4	fpBGA	256	IND	6.1K
LFECP6E-3Q208I	147	-3	PQFP	208	IND	6.1K
LFECP6E-4Q208I	147	-4	PQFP	208	IND	6.1K
LFECP6E-3T144I	97	-3	TQFP	144	IND	6.1K
LFECP6E-4T144I	97	-4	TQFP	144	IND	6.1K

Part Number	I/Os	Grade	Package	Pins	Temp.	LUTs
LFECP10E-3F484I	288	-3	fpBGA	484	IND	10.2K
LFECP10E-4F484I	288	-4	fpBGA	484	IND	10.2K
LFECP10E-3F256I	195	-3	fpBGA	256	IND	10.2K
LFECP10E-4F256I	195	-4	fpBGA	256	IND	10.2K
LFECP10E-3Q208I	147	-3	PQFP	208	IND	10.2K
LFECP10E-4Q208I	147	-4	PQFP	208	IND	10.2K

Part Number	I/Os	Grade	Package	Pins	Temp.	LUTs
LFECP15E-3F484I	352	-3	fpBGA	484	IND	15.3K
LFECP15E-4F484I	352	-4	fpBGA	484	IND	15.3K
LFECP15E-3F256I	195	-3	fpBGA	256	IND	15.3K
LFECP15E-4F256I	195	-4	fpBGA	256	IND	15.3K

LatticeECP Commercial

Part Number	I/Os	Grade	Package	Pins/Balls	Temp.	LUTs
LFECP6E-3FN484C	224	-3	Lead-Free fpBGA	484	COM	6.1K
LFECP6E-4FN484C	224	-4	Lead-Free fpBGA	484	COM	6.1K
LFECP6E-5FN484C	224	-5	Lead-Free fpBGA	484	COM	6.1K
LFECP6E-3FN256C	195	-3	Lead-Free fpBGA	256	COM	6.1K
LFECP6E-4FN256C	195	-4	Lead-Free fpBGA	256	COM	6.1K
LFECP6E-5FN256C	195	-5	Lead-Free fpBGA	256	COM	6.1K
LFECP6E-3QN208C	147	-3	Lead-Free PQFP	208	COM	6.1K
LFECP6E-4QN208C	147	-4	Lead-Free PQFP	208	COM	6.1K
LFECP6E-5QN208C	147	-5	Lead-Free PQFP	208	COM	6.1K
LFECP6E-3TN144C	97	-3	Lead-Free TQFP	144	COM	6.1K
LFECP6E-4TN144C	97	-4	Lead-Free TQFP	144	COM	6.1K
LFECP6E-5TN144C	97	-5	Lead-Free TQFP	144	COM	6.1K

Part Number	I/Os	Grade	Package	Pins/Balls	Temp.	LUTs
LFECP10E-3FN484C	288	-3	Lead-Free fpBGA	484	COM	10.2K
LFECP10E-4FN484C	288	-4	Lead-Free fpBGA	484	COM	10.2K
LFECP10E-5FN484C	288	-5	Lead-Free fpBGA	484	COM	10.2K
LFECP10E-3FN256C	195	-3	Lead-Free fpBGA	256	COM	10.2K
LFECP10E-4FN256C	195	-4	Lead-Free fpBGA	256	COM	10.2K
LFECP10E-5FN256C	195	-5	Lead-Free fpBGA	256	COM	10.2K
LFECP10E-3QN208C	147	-3	Lead-Free PQFP	208	COM	10.2K
LFECP10E-4QN208C	147	-4	Lead-Free PQFP	208	COM	10.2K
LFECP10E-5QN208C	147	-5	Lead-Free PQFP	208	COM	10.2K

Part Number	I/Os	Grade	Package	Pins/Balls	Temp.	LUTs
LFECP15E-3FN484C	352	-3	Lead-Free fpBGA	484	COM	15.3K
LFECP15E-4FN484C	352	-4	Lead-Free fpBGA	484	COM	15.3K
LFECP15E-5FN484C	352	-5	Lead-Free fpBGA	484	COM	15.3K
LFECP15E-3FN256C	195	-3	Lead-Free fpBGA	256	COM	15.3K
LFECP15E-4FN256C	195	-4	Lead-Free fpBGA	256	COM	15.3K
LFECP15E-5FN256C	195	-5	Lead-Free fpBGA	256	COM	15.3K

Part Number	I/Os	Grade	Package	Pins/Balls	Temp.	LUTs
LFECP20E-3FN672C	400	-3	Lead-Free fpBGA	672	COM	19.7K
LFECP20E-4FN672C	400	-4	Lead-Free fpBGA	672	COM	19.7K
LFECP20E-5FN672C	400	-5	Lead-Free fpBGA	672	COM	19.7K
LFECP20E-3FN484C	400	-3	Lead-Free fpBGA	484	COM	19.7K
LFECP20E-4FN484C	400	-4	Lead-Free fpBGA	484	COM	19.7K
LFECP20E-5FN484C	400	-5	Lead-Free fpBGA	484	COM	19.7K

Part Number	I/Os	Grade	Package	Pins/Balls	Temp.	LUTs
LFECP33E-3FN672C	496	-3	Lead-Free fpBGA	672	COM	32.8K
LFECP33E-4FN672C	496	-4	Lead-Free fpBGA	672	COM	32.8K
LFECP33E-5FN672C	496	-5	Lead-Free fpBGA	672	COM	32.8K

LatticeECP Commercial (Continued)

Part Number	I/Os	Grade	Package	Pins/Balls	Temp.	LUTs
LFECP33E-3FN484C	360	-3	Lead-Free fpBGA	484	COM	32.8K
LFECP33E-4FN484C	360	-4	Lead-Free fpBGA	484	COM	32.8K
LFECP33E-5FN484C	360	-5	Lead-Free fpBGA	484	COM	32.8K

LatticeEC Industrial

Part Number	I/Os	Grade	Package	Pins/Balls	Temp.	LUTs
LFEC1E-3QN208I	112	-3	Lead-Free PQFP	208	IND	1.5K
LFEC1E-4QN208I	112	-4	Lead-Free PQFP	208	IND	1.5K
LFEC1E-3TN144I	97	-3	Lead-Free TQFP	144	IND	1.5K
LFEC1E-4TN144I	97	-4	Lead-Free TQFP	144	IND	1.5K
LFEC1E-3TN100I	67	-3	Lead-Free TQFP	100	IND	1.5K
LFEC1E-4TN100I	67	-4	Lead-Free TQFP	100	IND	1.5K

Part Number	I/Os	Grade	Package	Pins/Balls	Temp.	LUTs
LFEC3E-3FN256I	160	-3	Lead-Free fpBGA	256	IND	3.1K
LFEC3E-4FN256I	160	-4	Lead-Free fpBGA	256	IND	3.1K
LFEC3E-3QN208I	145	-3	Lead-Free PQFP	208	IND	3.1K
LFEC3E-4QN208I	145	-4	Lead-Free PQFP	208	IND	3.1K
LFEC3E-3TN144I	97	-3	Lead-Free TQFP	144	IND	3.1K
LFEC3E-4TN144I	97	-4	Lead-Free TQFP	144	IND	3.1K
LFEC3E-3TN100I	67	-3	Lead-Free TQFP	100	IND	3.1K
LFEC3E-4TN100I	67	-4	Lead-Free TQFP	100	IND	3.1K

Part Number	I/Os	Grade	Package	Pins/Balls	Temp.	LUTs
LFEC6E-3FN484I	224	-3	Lead-Free fpBGA	484	IND	6.1K
LFEC6E-4FN484I	224	-4	Lead-Free fpBGA	484	IND	6.1K
LFEC6E-3FN256I	195	-3	Lead-Free fpBGA	256	IND	6.1K
LFEC6E-4FN256I	195	-4	Lead-Free fpBGA	256	IND	6.1K
LFEC6E-3QN208I	147	-3	Lead-Free PQFP	208	IND	6.1K
LFEC6E-4QN208I	147	-4	Lead-Free PQFP	208	IND	6.1K
LFEC6E-3TN144I	97	-3	Lead-Free TQFP	144	IND	6.1K
LFEC6E-4TN144I	97	-4	Lead-Free TQFP	144	IND	6.1K

Part Number	I/Os	Grade	Package	Pins/Balls	Temp.	LUTs
LFEC10E-3FN484I	288	-3	Lead-Free fpBGA	484	IND	10.2K
LFEC10E-4FN484I	288	-4	Lead-Free fpBGA	484	IND	10.2K
LFEC10E-3FN256I	195	-3	Lead-Free fpBGA	256	IND	10.2K
LFEC10E-4FN256I	195	-4	Lead-Free fpBGA	256	IND	10.2K
LFEC10E-3QN208I	147	-3	Lead-Free PQFP	208	IND	10.2K
LFEC10E-4QN208I	147	-4	Lead-Free PQFP	208	IND	10.2K